

ABSTRACT

An IC socket is provided which is configured to suppress any power source noises and waveform distortions produced by parasitic inductances of a power source probe contact and a signaling probe contact, or to prevent the occurrence of impedance mismatching. A multi-layer printed board 20 having at least four conductor layers embedded therein including ground conductor layers 23, 25 and power source conductor layers 22, 24 alternately laminated one on another at predetermined spacings is provided with a plurality of through-hole conductors 21a, 21a', 21b, 21c, and probe contacts 3a, 3b, 3c adapted to be electrically contacted with terminals of a DUT 4 are attached to the through-hole conductors 21a, 21b, 21c other than at least one 21a' of those through-hole conductors. The ground conductor layers are electrically connected with the ground through-hole conductors 21a, 21a', and the power source conductor layers are electrically connected with the power source through-hole conductor 21b, and capacitors CA, CB are produced, with the material of the printed board 20 as a dielectric, between the ground conductor layers and the power source conductor layers.